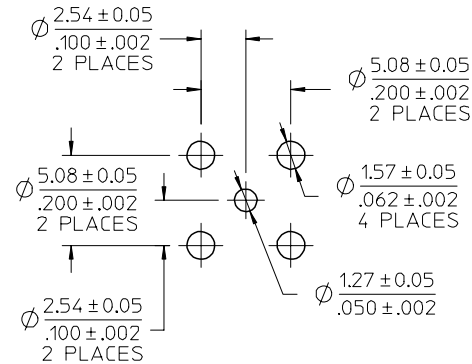
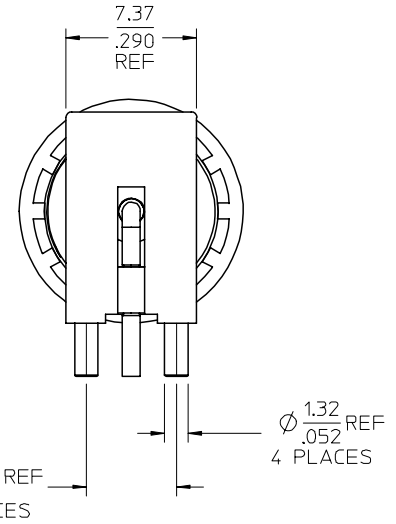
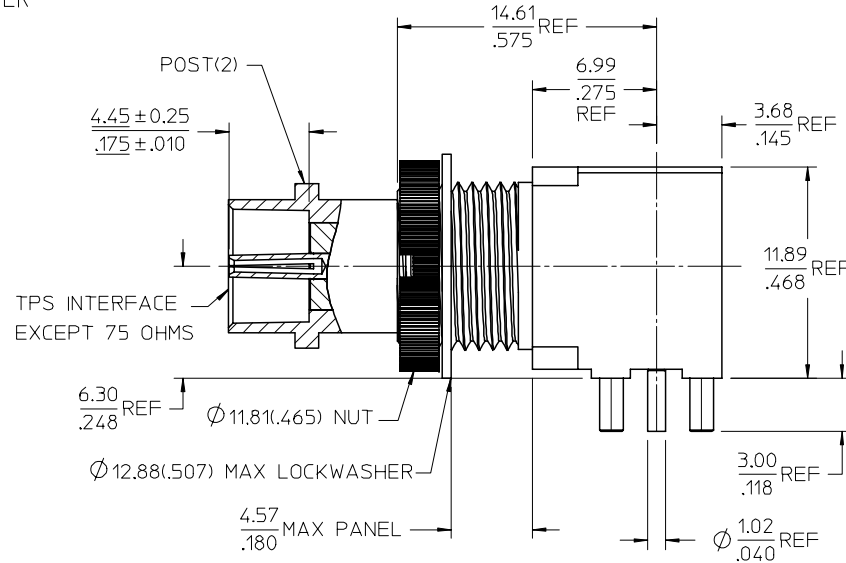
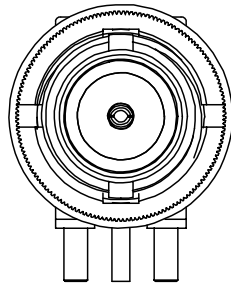
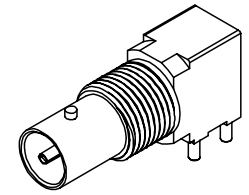


MATERIALS AND FINISHES

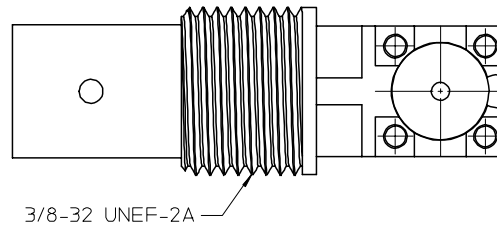
BODY ZINC
PLATED SEE TABLE

CENTER CONTACT BERYLLIUM COPPER
PLATED GOLD

INSULATOR TEFLON (PTFE)



RECOMMENDED PCB LAYOUT



73415-2204	SINGLE BAG VERSION OF 73415-2202
73415-2203	SINGLE BAG VERSION OF 73415-2201
73415-2202	NICKEL
73415-2201	GOLD 10 μ INCHES MAX OVER NICKEL 100 μ INCHES
73415-2200	OBSOLETE
PART NO.	PLATING

CHG: ADDED -2203 & -2204. EC NO: URF2007-0254 DRAWN: ARROBERTSON 2007/01/04 CHKD: 2007/01/04 APPR: JIM ENEVER 2007/01/04 B2	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± --- ANGULAR ± 2 °	mm INCH ± --- ± --- ± --- ± --- ± --- ± --- ± --- ± ---	DRAWN BY SSS	DATE 2000/06/26	TITLE TPS JACK, R/A, PCB BLKHD, 75 OHMS EWR-1090 TPS-J/PCB	MOLEX MOLEX INCORPORATED	SHEET NO. 1 OF 1
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO. SD-73415-220		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		